

General Description

This silicon carbide Power MOSFET device has been developed using ZMJ's advanced 1st generation SiC MOSFET technology. The device features a very low $R_{DS(on)}$ over the entire temperature range combined with low capacitances and very high switching operations. It improves application performance in frequency, energy efficiency, system size and weight reduction.

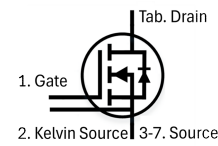
Features

- High Blocking Voltage
- High Speed Switching With Low Capacitances
- Low $R_{DS(on)}$ to Minimize Conductive Loss
- Low Gate Charge For Fast Switching
- Low Thermal Resistance
- 100% Avalanche Tested

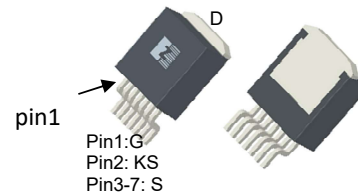
Application

- Motor Drives
- DC-DC
- Switched Mode Power Supply
- Auxiliary Power Supply

Product Summary



$V_{DS} = 3300V$
 $R_{DS(on)} = 640m\Omega$
 $I_D = 6A$



TO-263-7



Ordering Information:

Part NO.	ZMC100KR330B7
Marking	ZMC100KR330
Packing Information	REEL TAPE
Basic Ordering Unit (pcs)	800

Absolute Maximum Ratings ($T_C=25^\circ C$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		3300	V
Gate-Source Voltage	V_{GS}	Transient Voltage	-10V/25V	V
	V_{GS}	Static Voltage	-10V/20V	V
Recommended Turn On Gate Voltage	$V_{GS(on)}$		18 to 20V	V
Recommended Turn Off Gate Voltage	$V_{GS(off)}$		-5V to 0V	V
Continuous Drain Current	I_D	$V_{GS}=20V, T_C=25^\circ C$	6	A
	I_D	$V_{GS}=20V, T_C=75^\circ C$	5	A
	I_D	$V_{GS}=20V, T_C=100^\circ C$	4	A

Pulsed Drain Current ^①	I_{DM}	Pulsed; $t_p \leq 10 \mu s$; $T_{mb} = 25^\circ C$;	24	A
Total Power Dissipation	P_D	$T_C = 25^\circ C$	75	W
Total Power Dissipation	P_D	$T_A = 25^\circ C$	2.4	W
Operating Junction Temperature	T_J		-55 to +175	$^\circ C$
Storage Temperature	T_{STG}		-55 to +175	$^\circ C$
ESD Level (HBM)	Class2			

• Thermal Resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal Resistance, Junction - Case	R_{thJC}	-	-	2	$^\circ C/W$
Thermal Resistance, Junction-Ambient	R_{thJA} ②	-	-	62	$^\circ C/W$
Soldering Temperature(total time<10s)	T_{sld}	-	-	260	$^\circ C$

• Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 100\mu A$	3300	-	-	V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}, I_D = 2mA$	3	4.4	5	V
		$V_{GS} = V_{DS}, I_D = 2mA, T_J = 175^\circ C$	-	3.2	-	
Drain-Source Leakage Current	I_{DSS}	$V_{GS} = 0V, V_{DS} = 3300V$	-	-	10	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS} = -10V, V_{DS} = 0V$	-	-	-100	nA
		$V_{GS} = 25V, V_{DS} = 0V$	-	-	100	nA
Static Drain-Source On Resistance	$R_{DS(on)}$	$T_J = 25^\circ C, V_{GS} = 20V, I_D = 2A$	-	640	800	m Ω
		$T_J = 175^\circ C, V_{GS} = 20V, I_D = 2A$	-	1800	-	m Ω
		$T_J = 25^\circ C, V_{GS} = 18V, I_D = 2A$	-	690	-	m Ω
Forward Transconductance	g_{fs}	$V_{DS} = 10V, I_{SD} = 2A$	-	1	-	S
Diode Forward Voltage	V_{FSD}	$V_{GS} = -5V, I_{SD} = 2A$	-	3.9	5	V

• Dynamic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input Capacitance	C_{iss}	$f = 100KHz, V_{DS} = 1000V$	-	415	-	pF
Output Capacitance	C_{oss}		-	11	-	
Reverse Transfer Capacitance	C_{rss}		-	1.8	-	
Output Charge	Q_{oss}	$f = 100KHz, V_{GS} = 0V, V_{DS} = 0V \text{ to } 1000V$	-	26.4	-	nC
Coss Stored Energy	E_{oss}		-	9.5	-	μJ
Gate Resistance	R_g	$f = 1MHz$	-	4.8	-	Ω
Total Gate Charge	Q_g	$V_{DD} = 1000V, I_D = 2A, V_{GS} = -5V/20V$	-	24	-	nC
Gate - Source Charge	Q_{gs}		-	6	-	
Gate - Drain Charge	Q_{gd}		-	14	-	

Characteristics Diagrams

Fig.1 Gate-Charge Characteristics

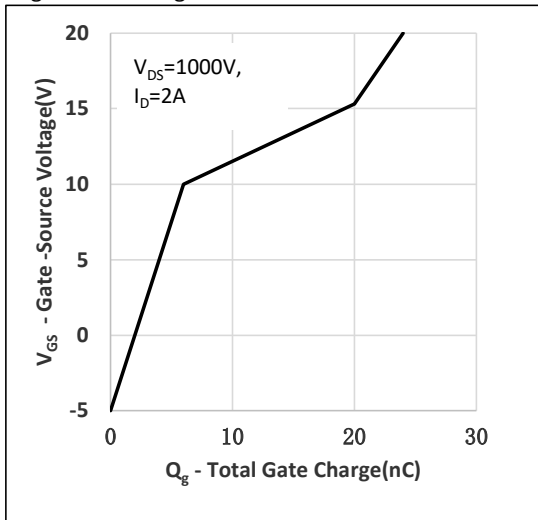


Fig.2 Capacitance Characteristics

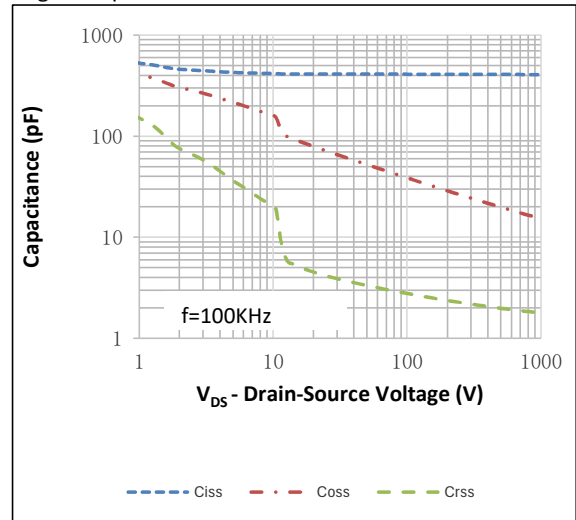


Fig.3 Power Dissipation

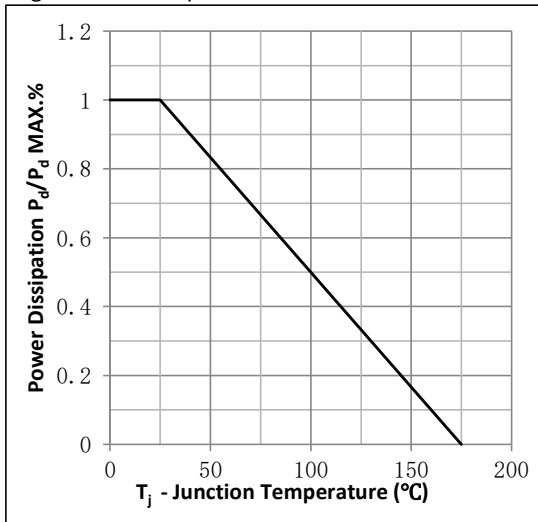


Fig.4 Typical Output Characteristics

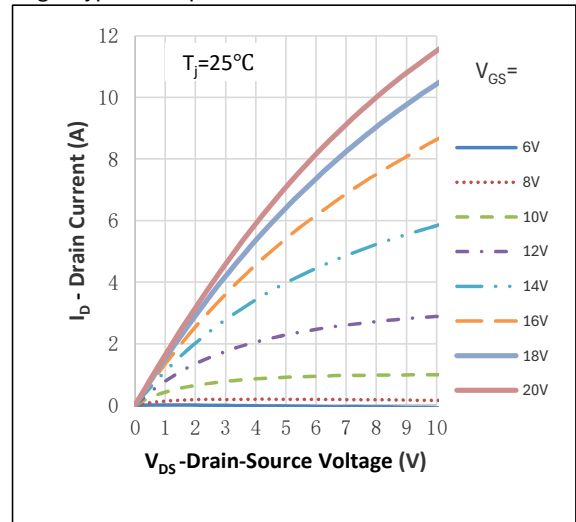


Fig.5 Threshold Voltage vs. Junction Temperature

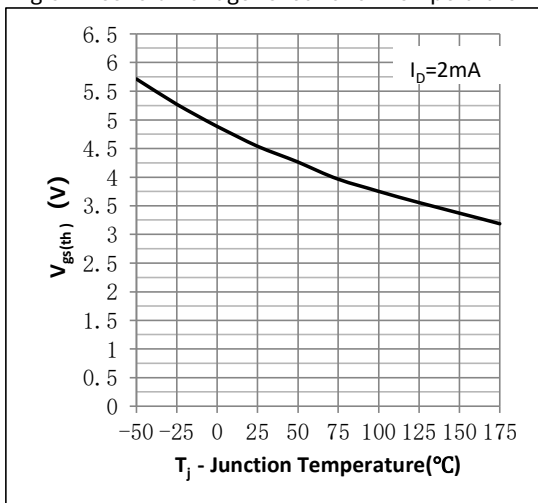


Fig.6 On-Resistance vs. Drain Current

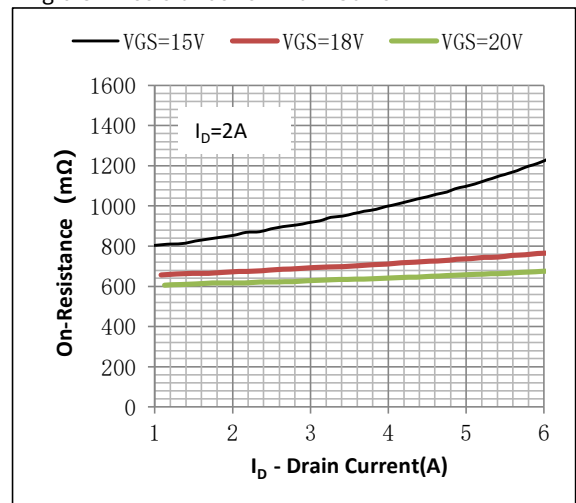


Fig.7 On-Resistance vs. Gate Source Voltage

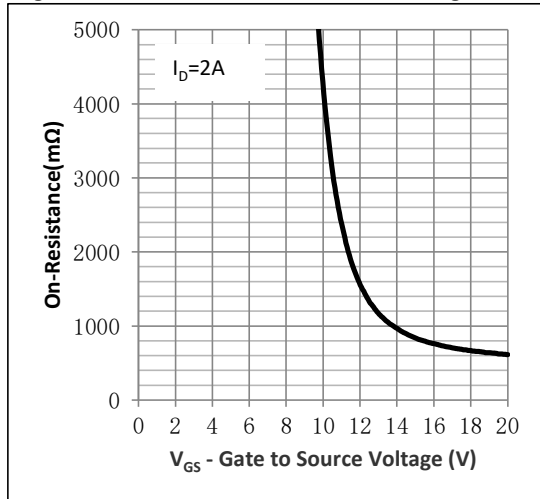


Figure 9. Diode Forward Voltage vs. Current

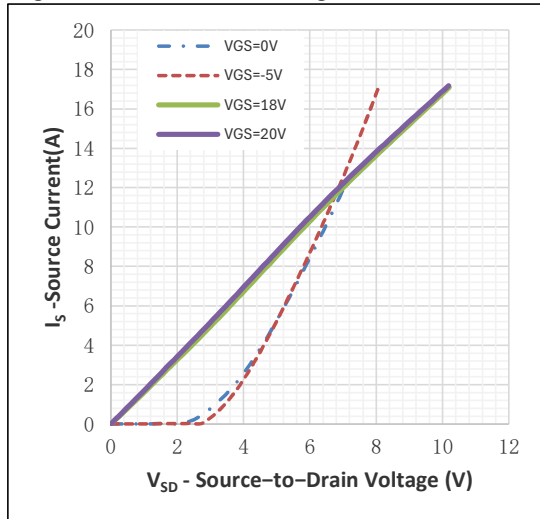


Fig.11 SOA Maximum Safe Operating Area

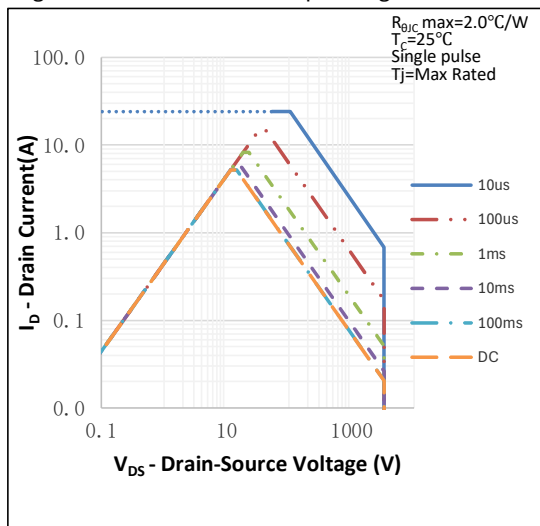


Fig.8 On-Resistance vs. Junction Temperature

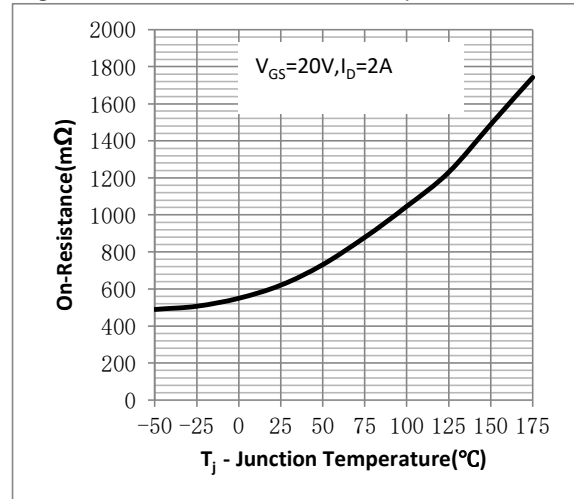


Figure 10. Transfer Characteristics

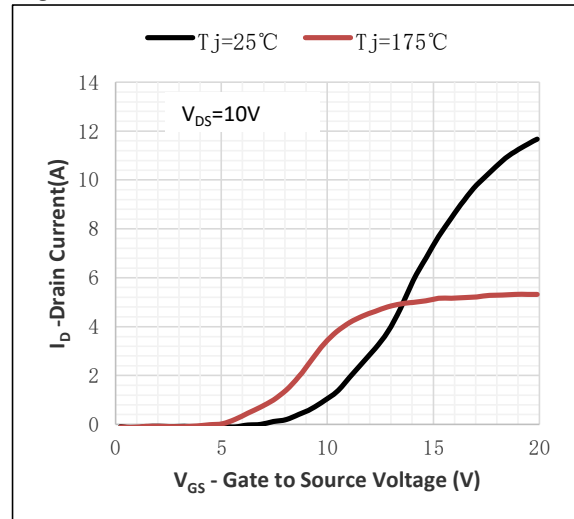


Fig.12 ID vs. Junction Temperature②

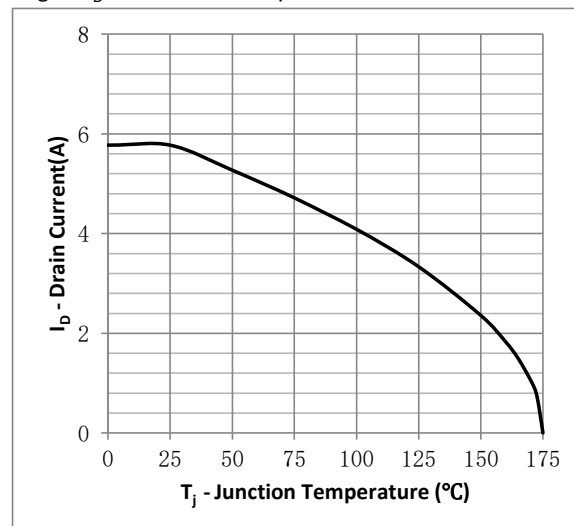


Fig.13 Output Capacitor Stored Energy

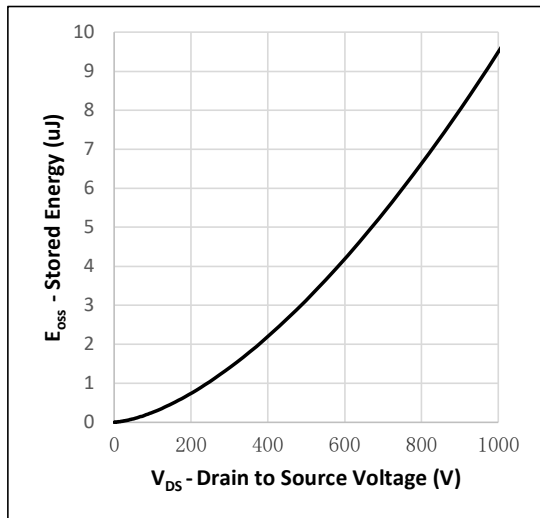
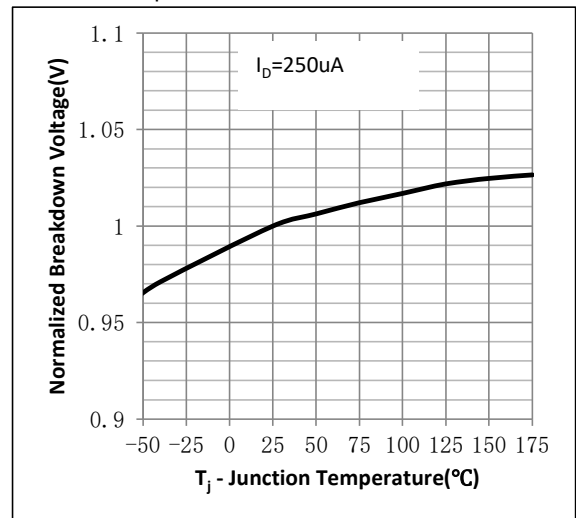
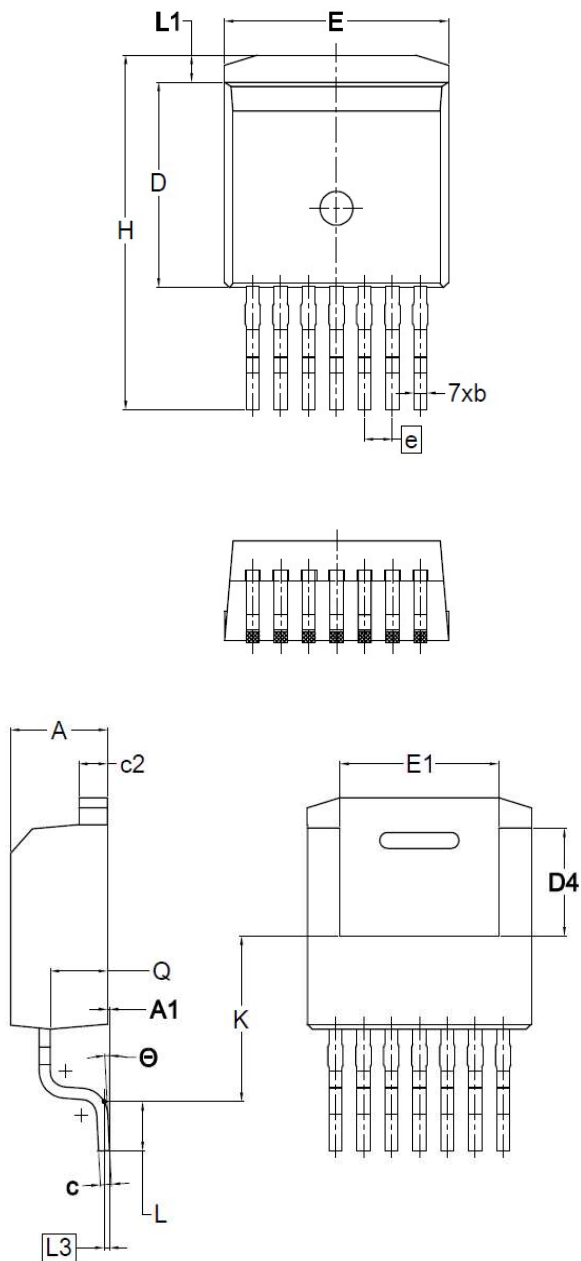


Fig.14 Normalized Breakdown Voltage vs. Junction Temperature



•TO-263-7 Package Outline



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	4.30	4.40	4.50
A1	0.00	0.10	0.25
b	0.50	0.60	0.70
c	0.45	0.50	0.60
c2	1.20	1.30	1.40
D	8.93	9.08	9.23
D4	4.65	4.80	4.95
E	10.08	10.18	10.28
E1	6.82	7.22	7.62
e	1.27 BSC		
H	15.00	15.70	16.00
K	7.30		
L	1.90	2.20	2.50
L1	1.00	1.20	1.40
L3	0.25 BSC		
Q	2.45	2.60	2.75
Θ	0°	3°	7°

Note:

- ① The value of $R_{\theta JA}$ is measured with the device in a still environment with $T_A=25^{\circ}\text{C}$
- ② Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=18\text{V}$.

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Revision History:

Version	Date	Change
A	2024/11/20	New